External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Solder Wire	Pure metal	Tin (Sn)	7440-31-5	0.00747	5.0	0.399
	Pure metal	Silver (Ag)	7440-22-4	0.00224	1.5	0.1197
	Pure metal	Lead (Pb)	7439-92-1	0.13969	93.5	7.4613
			Subtotal	0.1494	100	7.98
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.11982	100.0	6.4
			Subtotal	0.11982	100	6.4
Lead Frame		Phosphorous (P)	7723-14-0	0.01891	0.03	1.00983
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.6806	1.08	36.35388
		Copper (Cu)	7440-50-8	62.31861	98.89	3,328.73629
			Subtotal	63.01812	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.6745	7.7	142.8581
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.16806	12.0	222.636
	Filler	Silica fused	60676-86-0	27.78706	80.0	1,484.24
	Carbon Black	Carbon black	1333-86-4	0.1042	0.3	5.5659
			Subtotal	34.73382	100	NaN
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.79164	100.0	95.7
			Subtotal	1.79164	100	95.7
Die		Lead Dioxide (PbO2)	1309-60-0	0.00124	0.66	0.066
	Doped silicon	Silicon (Si)	7440-21-3	0.18598	99.34	9.934
			Subtotal	0.18722	100	10
			Total	100.00002	100	NaN

Disclaimer